

### Description

The AO6800-HXY uses advanced trench technology

to provide excellent  $R_{\text{DS}(\text{ON})},$  low gate charge and

operation with gate voltages as low as 2.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

### **General Features**

VDS = 30V ID = 4.5A

 $R_{DS(ON)} < 38m\Omega @ V_{GS}=10 V$ 

# Application

Battery protection

Load switch

Uninterruptible power supply

#### Package Marking and Ordering Information

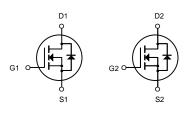
Product ID	Pack	Marking	Qty(PCS)
AO6800-HXY	SOT-23-6L	6800 XXX YYYY	3000

# Absolute Maximum Ratings@Tj=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	<u>+</u> 20	
I₀@T₄=25℃	Drain Current, V <sub>GS</sub> @ 4.5V <sup>3</sup>	4.5	А
Ідм	Pulsed Drain Current <sup>1</sup>	15	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation	1.25	W
Тята	Storage Temperature Range	-55 to 150	°C
Tj	Operating Junction Temperature Range	-55 to 150	°C
Rthj-a	Maximum Thermal Resistance, Junction- ambient <sup>3</sup>	125	°C/W



SOT-23-6L



Dual N-Channel MOSFET



# Electrical Characteristics (T\_J=25°C unless otherwise specified)

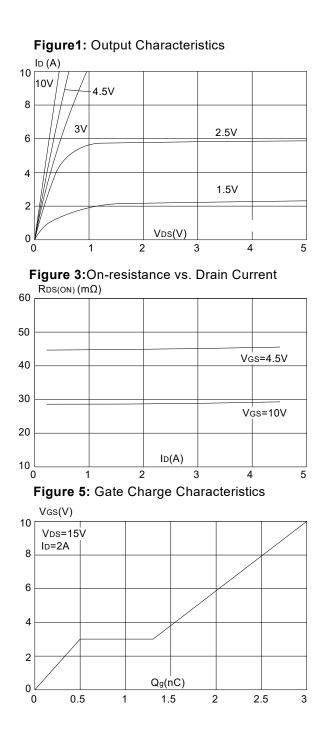
Symbol	Parameter	<b>Test Condition</b>	Min.	Тур.	Max.	Units
Off Charac	teristic			1		
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250µA	30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V,	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
On Charac	teristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA	1.0	1.5	2.5	V
<b>D</b>	Static Drain-Source on-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =4A	-	29	38	
$R_{DS(on)}$		V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A	-	45	65	mΩ
Dynamic C	Characteristics					
Ciss	Input Capacitance		-	233	-	pF
Coss	Output Capacitance	─ V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, ─ f=1.0MHz	-	44	-	pF
Crss	Reverse Transfer Capacitance		-	33	-	pF
Qg	Total Gate Charge		-	3	-	nC
$Q_{gs}$	Gate-Source Charge	V <sub>DS</sub> =15V, I <sub>D</sub> =2A, V <sub>GS</sub> =10V	-	0.5	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge	VGS-10V	-	0.8	-	nC
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-on Delay Time		-	4	-	ns
t <sub>r</sub>	Turn-on Rise Time	$-V_{DS}=15V,$	-	2.1	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time	─ I <sub>D</sub> =4A, R <sub>GEN</sub> =3Ω, ─ V <sub>GS</sub> =10V	-	15	-	ns
t <sub>f</sub>	Turn-off Fall Time	- V <sub>GS</sub> -10V	-	3.2	-	ns
Drain-Sou	rce Diode Characteristics and Maxim	um Ratings				
ls	Maximum Continuous Drain to Source Diode Forward Current		-	-	4.5	А
Ism	Maximum Pulsed Drain to Source Diode Forward Current		-	-	16	Α
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =4A	-	-	1.2	V

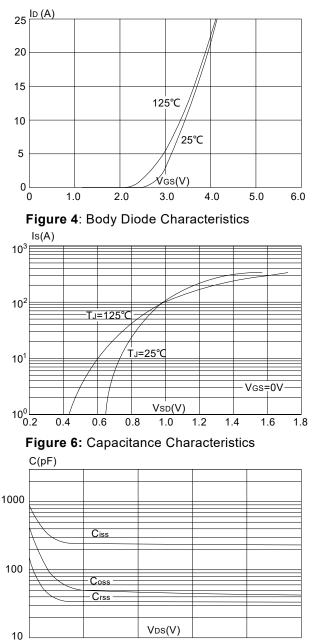
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



# **Typical Performance Characteristics**





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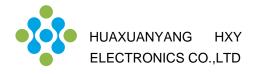
10

15

20

25

Figure 2: Typical Transfer Characteristics



**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature

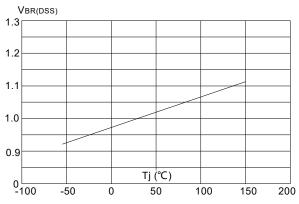
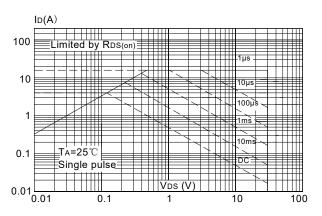
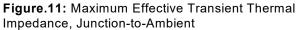
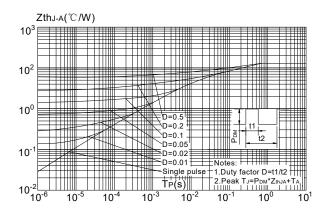


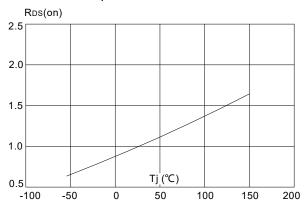
Figure 9: Maximum Safe Operating Area



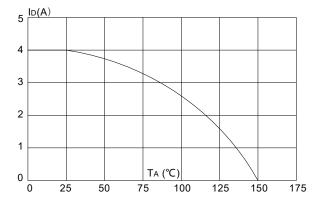


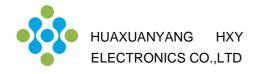


**Figure 8:** Normalized on Resistance vs. Junction Temperature

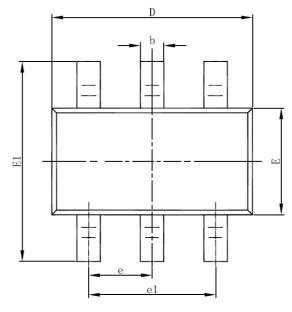


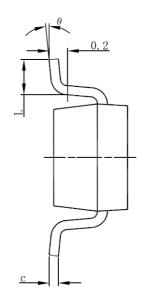
**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature

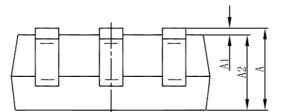




#### SOT-23-6L Package Information







Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
A	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	



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